

Title (en)  
ADHESIVE APPLICATION PROCESS

Publication  
**EP 0245325 B1 19901128 (DE)**

Application  
**EP 86906322 A 19861025**

Priority  
DE 3538897 A 19851102

Abstract (en)  
[origin: WO8702624A1] In order to be able to use, in the production of books, humidifying PUR melting adhesive systems for the binding of the body of the book and the cover (1), the adhesive is applied to the cover (1) in a width which exceeds the thickness of the back of the book on both sides by about 0.5 to 20 mm.

IPC 1-7  
**B42C 9/00**

IPC 8 full level  
**B42C 7/00** (2006.01); **B42C 9/00** (2006.01); **B42D 3/00** (2006.01)

CPC (source: EP US)  
**B42C 7/00** (2013.01 - EP US); **B42D 3/002** (2013.01 - EP US); **Y10S 156/908** (2013.01 - EP US); **Y10T 156/1034** (2015.01 - EP US); **Y10T 428/31591** (2015.04 - EP US)

Designated contracting state (EPC)  
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DOCDB simple family (publication)  
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**EP 8600616 W 19861025**; DE 3538897 A 19851102; DE 3675937 T 19861025; EP 86906322 A 19861025; JP 50594086 A 19861025; US 35589589 A 19890519